

DATASHEET

SMD - Side View LEDs EAPL3809GA0



Features

- Lead frame package with individual 2 pins.
- Wide viewing angle.
- Soldering methods: IR reflow soldering.
- ESD protection.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br<900ppm,CI<900ppm,Br+CI<1500ppm).
- Precondition: Bases on JEDEC J-STD 020D Level 3

Descriptions

The EAPL3809GA0 is available in soft orange, green, blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the LED ideal for light guide application.

Applications

- LCD Back Light.
- Mobile phones.
- Indicators.
- Switch Lights.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Brilliant Green	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V _R	5	V	
Forward Current	lF	25	mA	
Peak Forward Current		100	A	
(Duty 1/10 @1KHz)	IFP	100	mA	
Power Dissipation	Pd	95	mW	
Operating Temperature	T _{opr}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +90	°C	
ESD	ESD	150	V	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 $^{\circ}$ C for 10 sec.		
		Hand Soldering : 350 $^\circ\!\mathrm{C}$ for 3 sec.		

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	180		450	mcd	I⊧=5mA
Viewing Angle	20 _{1/2}		120		deg	I _F =5mA
Peak Wavelength	λΡ		518		Nm	l⊧=5mA
Dominant Wavelength	λ_{d}	520		535	nm	I _F =5mA
Spectrum Radiation Bandwidth	$ riangle \lambda$		35		nm	l⊧=5mA
Forward Voltage	VF	2.50		3.50	V	I _F =5mA
Reverse Current	lr			50	$\mu \mathbf{A}$	VR=5V

Notes:

1. Tolerance of Luminous Intensity: ±11%

2. Tolerance of Dominant Wavelength : ±1nm

3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
S1	180	225	mcd	
S2	225	285		
T1	285	360		I⊧ =5mA
T2	360	450		

Note: Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Groups	Bin Code	Min.	Max.	Unit	Condition
	Х	520	525		
Y	Y	525	530	nm	l⊧ =5mA
	Z	530	535		

Note: Tolerance of Dominant Wavelength : ±1nm

Bin Range of Forward Voltage

Groups	Bin Code	Min.	Max.	Unit	Condition
B17	9	2.50	2.70		
	10	2.70	2.90		
	11	2.90	3.10	V	l _F =5mA
	12	3.10	3.30		
	13	3.30	3.50		

Note: Tolerance of Forward Voltage: ±0.1V.



Typical Electro-Optical Characteristics Curves



DATASHEET SMD Side View LEDs EAPL3809GA0

Package Dimension











Recommended soldering pad design









Moisture Resistant Packing Materials

Label Explanation



- · CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- · REF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Carrier Tape Dimensions; Loaded Quantity 2000 pcs Per Reel



Moisture Resistant Packing Process











Desiccant

Label



Precautions for Use

1. Over-current-proof

1.1 Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).



2. Storage

2.1 Moisture proof bag should only be opened immediately prior to usage.

2.2 Environment should be less than 30 $^\circ C$ and 60% RH when moisture proof bag is opened.

2.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

2.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

3. Soldering Condition

- 3.1 Pb-free solder temperature profile
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
- 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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